

VERTICAL BALL GRID ARRAY INTEGRATED CIRCUIT PACKAGE

ABSTRACT OF THE DISCLOSURE

5 An integrated circuit package (30, 32) for vertical
attachment as part of a high density module (200) comprising
a carrier (70) having an opening (86), routing strips (82),
conduits (84) and side surface terminals (100), the side
surface terminals (100) disposed on a side surface (92), which
10 side surface is common to the carrier (70) and the integrated
circuit package 30, 32. An adhesive layer (60), which
attaches a silicon chip (50) to a carrier (70), wire bonding
(80) electrically connecting the silicon chip (50) to the
routing strips (82) and potting material (90) filling the
15 opening (86), are also disclosed.